MICONDUCTOR TECHNICAL DATA

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0 to 700 kPa (0 to 100 PSI) **High Pressure, Temperature Compensated & Calibrated,** Silicon Pressure Sensors

The MPX2700A series device is a silicon piezoresistive pressure sensor providing a highly accurate and linear voltage output — directly proportional to the applied pressure. The sensor is a single monolithic silicon diaphragm with the strain gauge and a thin-film resistor network integrated on-chip. The sensor is laser trimmed for precise span and offset calibration and temperature compensation.

Features

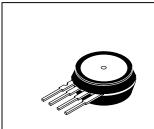
- Unique Silicon Shear Stress Strain Gauge
- ±1.0% Linearity
- Full Scale Span Calibrated to 40 mV
- · Easy to Use Chip Carrier Package
- Basic Element, Single Ported Devices Available

Application Examples

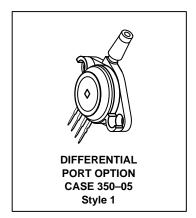
- Pump/Motor Controllers
- · Pneumatic Control
- · Tire Pressure Gauges
- Robotics
- Medical Diagnostics
- Pressure Switching
- Hydraulics

MPX2700A SERIES

X-ducer™ **SILICON** PRESSURE SENSORS



BASIC CHIP CARRIER ELEMENT CASE 344-11 Style 1



Pin Number				
1 2 3 4				
Ground	+V _{out}	٧S	-V _{out}	

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Overpressure (8) (P1 > P2)	P _{max}	2800	kPa
Burst Pressure ⁽⁸⁾ (P1 > P2)	P _{burst}	5000	kPa
Storage Temperature	T _{stg}	-40 to +125	°C
Operating Temperature	TA	-40 to +125	°C

VOLTAGE OUTPUT versus APPLIED DIFFERENTIAL PRESSURE

The differential voltage output of the X-ducer is directly proportional to the differential pressure applied.

The output voltage of the differential or gauge sensor increases with increasing pressure applied to the pressure side (P1) relative to the vacuum side (P2). Similarly, output voltage increases as increasing vacuum is applied to the vacuum side (P2) relative to the pressure side (P1).

Figure 1 shows a block diagram of the internal circuitry on the stand-alone pressure sensor chip.

X-ducer is a trademark of Motorola, Inc.

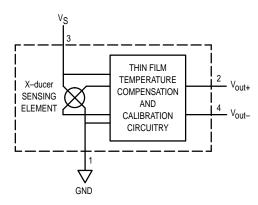


Figure 1. Temperature Compensated **Pressure Sensor Schematic**





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OPERATING CHARACTERISTICS ($V_{CC} = 10 \text{ Vdc}$, $T_A = 25^{\circ}\text{C}$ unless otherwise noted, P1 > P2)

Characteristic	Symbol	Min	Тур	Max	Unit
Pressure Range(1)	POP	0	_	700	kPa
Supply Voltage(2)	٧s	_	10	16	Vdc
Supply Current	Io	_	6.0	_	mAdc
Full Scale Span ⁽³⁾	VFSS	37.5	40	42.5	mV
Offset(4)	V _{off}	-2.0	_	2.0	mV
Sensitivity	ΔV/ΔΡ		0.057	_	mV/kPa
Linearity(5)	_	-1.0	_	1.0	%VFSS
Pressure Hysteresis ⁽⁵⁾ (0 to 700 kPa)	_	_	±0.1	_	%VFSS
Temperature Hysteresis ⁽⁵⁾ (–40°C to +125°C)		_	±0.5	_	%VFSS
Temperature Effect on Full Scale Span(5)	TCVFSS	-1.0	_	1.0	%VFSS
Temperature Effect on Offset ⁽⁵⁾	TCV _{off}	-1.0	_	1.0	mV
Input Impedance	z _{in}	1300	_	4000	Ω
Output Impedance	Z _{out}	1400	_	3000	Ω
Response Time ⁽⁶⁾ (10% to 90%)	t _R	_	1.0	_	ms
Offset Stability ⁽⁵⁾	_	_	±0.5	_	%VFSS

MECHANICAL CHARACTERISTICS

Characteristic	Symbol	Min	Тур	Max	Unit
Weight (Basic Element Case 344)	_	_	2.0	_	Grams
Warm-Up	_	_	15	_	Sec
Cavity Volume	_	_	_	0.01	Cubic In
Volumetric Displacement	_	_	_	0.001	Cubic In
Common Mode Line Pressure(7)	_	_	_	690	kPa

NOTES:

- 1. 1.0 kPa (kiloPascal) equals 0.145 psi.
- 2. Device is ratiometric within this specified excitation range. Operating the device above the specified excitation range may induce additional error due to device self—heating.
- 3. Full Scale Span (VFSS) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
- 4. Offset ($V_{\mbox{Off}}$) is defined as the output voltage at the minimum rated pressure.
- 5. Accuracy (error budget) consists of the following:
- Linearity: Output deviation from a straight line relationship with pressure, using end point method, over the specified

pressure range.

• Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is

cycled to and from the minimum or maximum operating temperature points, with zero differential pressure

applied.

• Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the

minimum or maximum rated pressure, at 25°C.

• Offset Stability: Output deviation, after 1000 temperature cycles, – 40 to 125°C, and 1.5 million pressure cycles, with zero

differential pressure applied.

• TcSpan: Output deviation at full rated pressure over the temperature range of 0 to 85°C, relative to 25°C.

TcOffset: Output deviation with minimum rated pressure applied, over the temperature range of 0 to 85°C, relative

to 25°C.

- 6. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
- 7. Common mode pressures beyond specified may result in leakage at the case-to-lead interface.
- 8. Exposure beyond these limits may cause permanent damage or degradation to the device.



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MPX2700A SERIES

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LINEARITY

Linearity refers to how well a transducer's output follows the equation: $V_{out} = V_{off} + sensitivity \times P$ over the operating pressure range. There are two basic methods for calculating nonlinearity: (1) end point straight line fit or (2) a least squares best line fit (see Figure 3). While a least squares fit gives the "best case" linearity error (lower numerical value), the calculations required are burdensome.

Conversely, an end point fit will give the "worst case" error (often more desirable in error budget calculations) and the calculations are more straightforward for the user. Motorola's specified pressure sensor linearities are based on the end point straight line method measured at the midrange pressure.

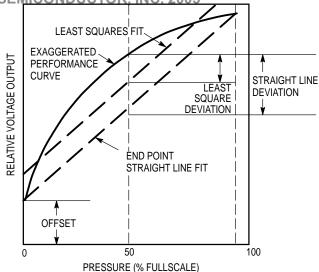


Figure 2. Linearity Specification Comparison

ON-CHIP TEMPERATURE COMPENSATION and CALIBRATION

Figure 3 shows the output characteristics of the MPX2700A series at 25°C. The output is directly proportional to the differential pressure and is essentially a straight line.

The effects of temperature on Full-Scale Span and Offset are very small and are shown under Operating Characteris-

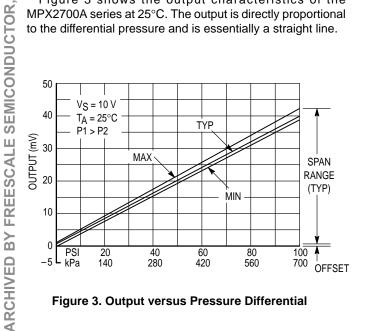


Figure 3. Output versus Pressure Differential

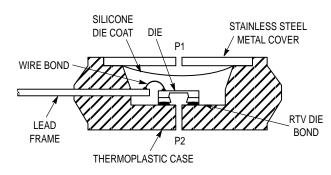


Figure 4. Cross-Section of Differential Pressure Sensor Die in Its Basic Package (Not to Scale)

Figure 4 shows the cross section of the Motorola MPX pressure sensor die in the chip carrier package. A silicone gel isolates the die surface and wire bonds from harsh environments, while allowing the pressure signal to be transmitted to the silicon diaphragm. MPX2700A series pressure sensor operating characteristics and internal reliability and qualification tests are based on use of dry air as the pressure media. Media other than dry air may have adverse effects on sensor performance and long term reliability. Contact the factory for information regarding media compatibility in your application.



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Motorola designates the two sides of the pressure sensor as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing silicone gel which protects the die from harsh media. The Motorola MPX pres-

sure sensor is designed to operate with positive differential pressure applied, P1 > P2.

The Pressure (P1) side may be identified by using the table below:

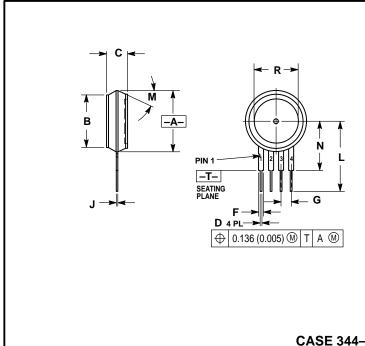
Part Number	Case Type	Pressure (P1) Side Identifier
MPX2700A	344–11	Stainless Steel Cap
MPX2700AP	350–05	Side with Port Attached
MPX2700ASX	371C-03	Side with Port Attached

ORDERING INFORMATION

MPX2700A series pressure sensors are available in various absolute configurations. Devices are available in the basic element package or with pressure port fittings which provide printed circuit board mounting ease and barbed hose pressure connections.

			MPX Series		
Device Type	Options	Case Type	Order Number	Device Marking	
Basic Element	Absolute	Case 344–11	MPX2700A	MPX2700A	
Ported Elements	Stovepipe	Case 350–05	MPX2700AP	MPX2700AP	
	Axial	Case 371C-03	MPX2700ASX	MPX2700A	





NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- DIMENSION -A- DOES NOT INCLUDE MOLDED FLASH RING. MOLDED FLASH RING NOT TO EXCEED 16.00 (0.630).

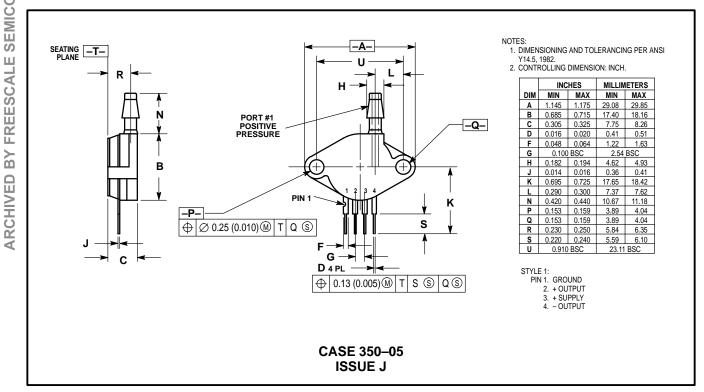
	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.595	0.620	15.11	15.75
В	0.514	0.534	13.06	13.56
С	0.200	0.220	5.08	5.59
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.40
L	0.695	0.725	17.65	18.42
M	30 ° NOM		30 ° NOM	
N	0.475	0.495	12.07	12.57
R	0.430	0.450	10.92	11.43

STYLE 1: PIN 1. GROUND 2. + OUTPUT 3. + SUPPLY

4. - OUTPUT

CASE 344-11 ISSUE R

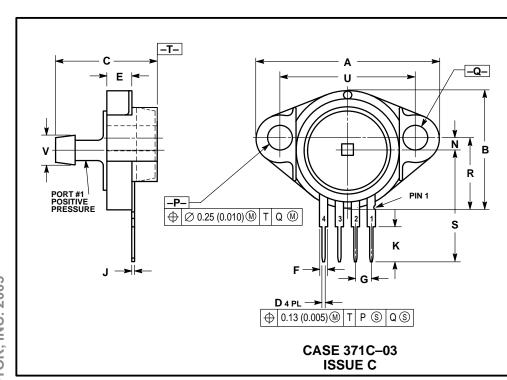
BASIC ELEMENT (A, D)



PRESSURE SIDE PORTED (AP, GP)



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PACKAGE DIMENSIONS — CONTINUED



- 1. DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	1.080	1.120	27.43	28.45	
В	0.740	0.760	18.80	19.30	
С	0.630	0.650	16.00	16.51	
D	0.016	0.020	0.41	0.51	
Е	0.160	0.180	4.06	4.57	
F	0.048	0.064	1.22	1.63	
G	0.100 BSC		2.54 BSC		
J	0.014	0.016	0.36	0.41	
K	0.220	0.240	5.59	6.10	
N	0.070	0.080	1.78	2.03	
Р	0.150	0.160	3.81	4.06	
Q	0.150	0.160	3.81	4.06	
R	0.440	0.460	11.18	11.68	
S	0.695	0.725	17.65	18.42	
U	0.840	0.860	21.34	21.84	
٧	0.182	0.194	4.62	4.92	

STYLE 1:

PIN 1. GROUND

2. V (+) OUT 3. V SUPPLY

4. V (-) OUT

PRESSURE SIDE PORTED (ASX, GSX)

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